

ENTEK PLUS IC

Organic Solderability Preservative

The Most Widely Used and Trusted OSP Brand on the Market

The ENTEK Organic Solderability Preservative (OSP) brand is the industry's most widely used and trusted in the market today.

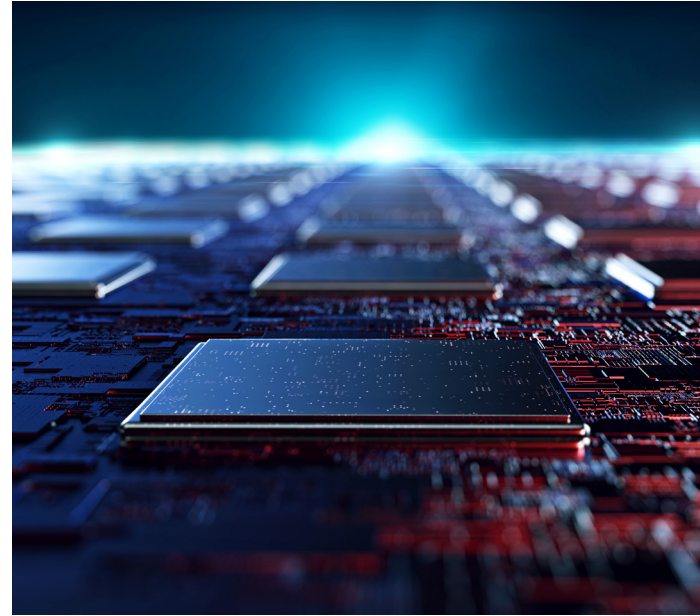
ENTEK PLUS IC is the latest addition to the ENTEK OSP family providing performance and yield improvement for substrate manufacturers.

ENTEK PLUS IC's industry leading thickness capability allows unrivalled shelf life of 24-months, providing supply chain flexibility and performance risk elimination associated with other OSP's. With proven resistance to de-flux materials, ENTEK PLUS IC OSP maintains thickness through cleaning operations while delivering reliable performance for subsequent assembly operations, while maximizing yield.

ENTEK PLUS IC OSP forms a copper-tin intermetallic which produces the strongest possible solder joint. Working in collaboration with Alpha Assembly, ENTEK PLUS IC's interaction with assembly materials has been optimized and verified through extensive solder-spread, ball-shear and drop shock testing.

KEY FEATURES

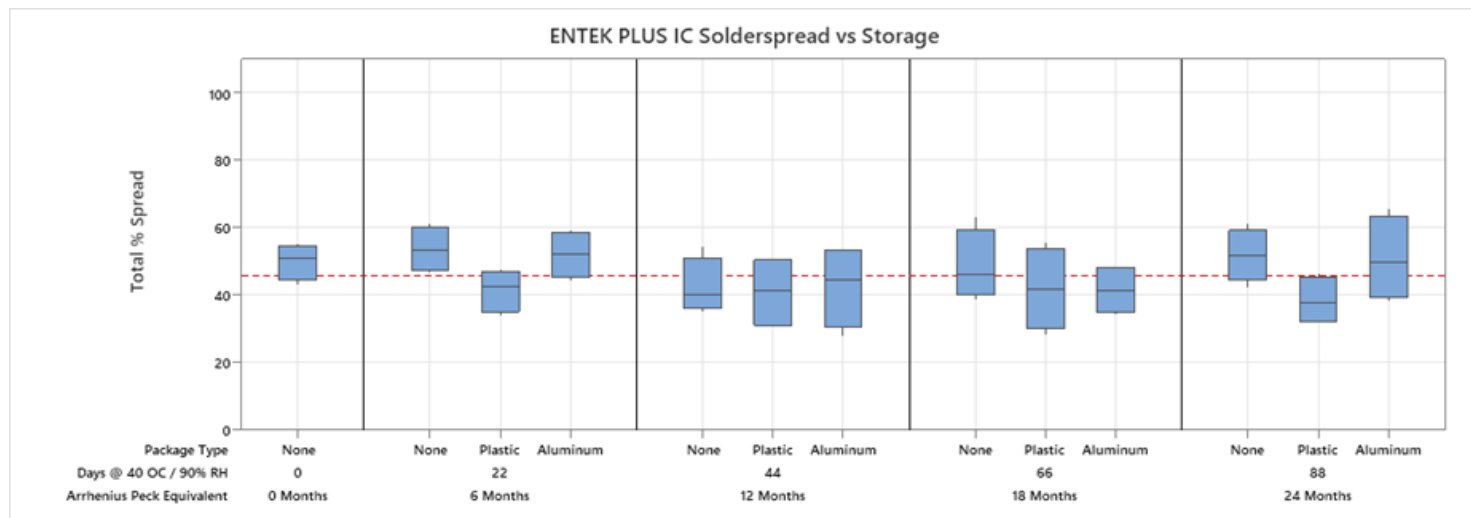
- Industry leading OSP coating thickness capability
- 24-months shelf life under best practice packaging and storage
- Visually unchanged while retaining performance after multiple reflows
- Significant minimization of OSP thickness reduction through de-flux, providing protection of copper surfaces for further assembly
- Optimized interaction with assembly materials for BGA ball attach technologies
- Compatible with mixed metal applications
- Environmentally friendly processing



ENTEK PLUS IC

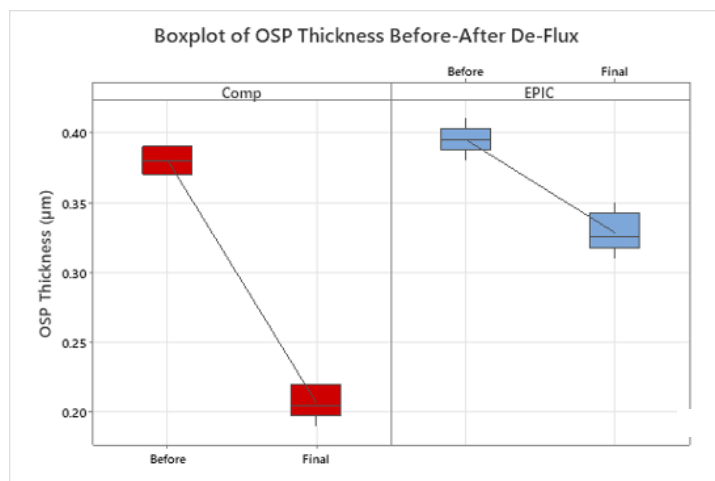
Organic Solderability Preservative

Industry Leading Shelf Life



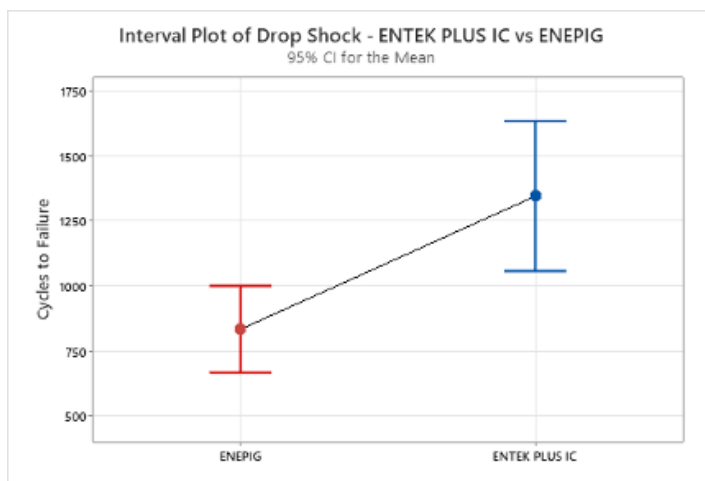
Shelf-life testing shows ENTEK PLUS IC OSP delivers consistent solder spread results up to 24-months of storage.

De-Flux Resistance



De-flux cleaning has the potential to remove OSP from copper circuitry which will cause yield issues with 2nd assembly operation. ENTEK PLUS IC has demonstrated robust thickness retention through de-flux while minimizing product losses.

High Reliability



ENTEK PLUS IC produces the preferred Cu-Sn intermetallic upon soldering. Extensive drop-shock testing shows ENTEK PLUS IC produces a solder joint with high reliability when exposed to free fall impact. Failure is defined as a drop of (greater than or equal to sign) 1V in the applied potential for at least 0.5 ms, based on the IPC/JEDEC-9706 standard.

